MICROPOWER, ULTRA-SENSITIVE HALL-EFFECT SWITCHES

Pinning is shown viewed from branded side.

Dwg. PH-016-1

ABSOLUTE MAXIMUM RATINGS at $T_A = +25^{\circ}C$

| Supply Voltage, V _{DD} 5 V |
|---|
| Magnetic Flux Density, B Unlimited |
| Output Off Voltage, V_{OUT} 5 V |
| Output Current, I _{OUT} 1 mA |
| Junction Temperature, T _J +170°C |
| Operating Temperature Range, |
| T_A 40°C to +85°C |
| Storage Temperature Range, |
| T_S 65°C to +170°C |
| Caution: These CMOS devices have input |

static protection (Class 3) but are still

extremely high static electrical charges.

susceptible to damage if exposed to

The A3209Ex and A3210Ex integrated circuits are ultra-sensitive, pole independent Hall-effect switches with a latched digital output. They are especially suited for operation in battery-operated, hand-held equipment such as cellular and cordless telephones, pagers, and palmtop computers. 2.5 volt to 3.5 volt operation and a unique clocking scheme to reduce the average operating power requirements – the A3209Ex to 400 μW , the A3210Ex to 25 $\mu W!$ Except for operating duty cycle and average operating current, the A3209Ex and A3210Ex are identical.

Unlike other Hall-effect switches, either a north <u>or</u> south pole of sufficient strength will turn the output on; in the absence of a magnetic field, the output is off. The polarity independence and minimal power requirement allows these devices to easily replace reed switches for superior reliability and ease of manufacturing, while eliminating the requirement for signal conditioning.

Improved stability is made possible through chopper stabilization (dynamic offset cancellation), which reduces the residual offset voltage normally caused by device overmolding, temperature dependencies, and thermal stress.

These devices include on a single silicon chip a Hall-voltage generator, small-signal amplifier, chopper stabilization, a latch, and a MOSFET output. Advanced BiCMOS processing is used to take advantage of low-voltage and low-power requirements, component matching, very low input-offset errors, and small component geometries.

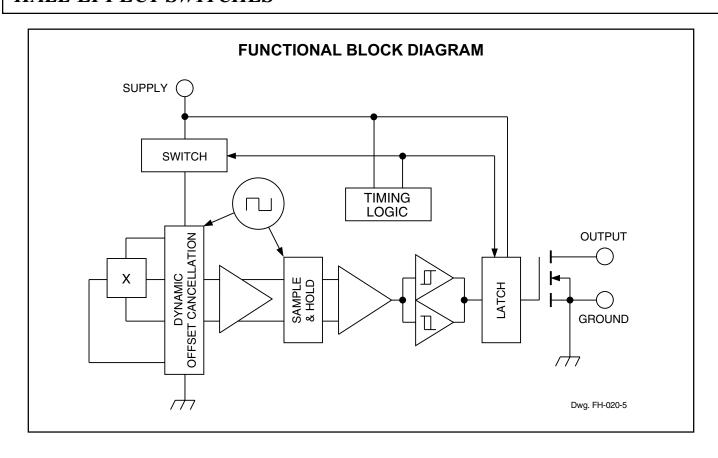
The A3209Ex and A3210Ex are rated for operation over a temperature range of -40°C to +85°C. Two package styles provide a magnetically optimized package for most applications. Suffix 'LH' is a miniature low-profile surface-mount package while suffix 'UA' is a three-lead ultra-mini-SIP for through-hole or surface mounting.

FEATURES

- Micropower Operation
- Operate With North or South Pole
- 2.5 V to 3.5 V Battery Operation
- Chopper Stabilized
 Superior Temperature Stability
 Extremely Low Switch-Point Drift
 Insensitive to Physical Stress
- ESD Protected to 5 kV
- Solid-State Reliability
- Small Size
- Easily Manufacturable With Magnet Pole Independence

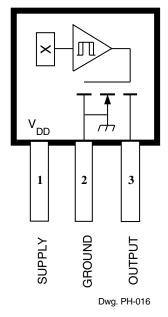
Always order by complete part number: the prefix 'A' + the basic four-digit part number + the suffix 'E' to indicate operating temperature range + a suffix to indicate package style, e.g., [A3210ELH].





TOWER DISSIPATION IN THE PACKAGE DOWNER DISSIPATION IN THE PACKAGE DISSIPATION IN THE P

Package Suffix 'UA' Pinning



Pinning is shown viewed from branded side.



ELECTRICAL CHARACTERISTICS with $C_{BYPASS} = 0.1 \mu F$, over operating voltage and temperature range (unless otherwise specified).

| | | | Limits | | | |
|---|----------------------|--|--------|------|------|-------|
| Characteristic | Symbol | Test Conditions | Min. | Тур. | Max. | Units |
| Supply Voltage Range | V_{DD} | Operating ¹⁾ | 2.5 | 2.75 | 3.5 | V |
| Output Leakage Current | I _{OFF} | V_{OUT} = 3.5 V, B_{RPN} < B < B_{RPS} | _ | «1.0 | 1.0 | μΑ |
| Output On Voltage | V _{OUT} | I _{OUT} = 1 mA, V _{DD} = 2.5 V | _ | 105 | 300 | mV |
| Awake Time | t _{awake} | | 30 | 60 | 90 | μs |
| Period | t _{period} | A3209Ex | 240 | 480 | 720 | μs |
| | | A3210Ex | 30 | 60 | 90 | ms |
| Duty Cycle | d.c. | A3209Ex | _ | 12.5 | _ | % |
| | | A3210Ex | _ | 0.10 | _ | % |
| Chopping Frequency | f _C | | - | 340 | _ | kHz |
| Supply Current $(2.5 \le V_{DD} \le 3.5 \text{ V})$ | I _{DD(EN)} | Chip awake (enabled) | 0.1 | _ | 3.0 | mA |
| | I _{DD(DIS)} | Chip asleep (disabled) | 1.0 | 10 | 50 | μА |
| | I _{DD(AVG)} | A3209Ex, V _{DD} = 2.75 V | _ | 145 | 425 | μΑ |
| | | A3209Ex, V _{DD} = 3.5 V | _ | 195 | 425 | μА |
| | | A3210Ex, V _{DD} = 2.75 V | _ | 8.8 | 25 | μА |
| | | A3210Ex, V _{DD} = 3.5 V | | 13 | 60 | μΑ |

NOTES: 1. Operate and release points will vary with supply voltage.

- 2. B_{OPx} = operate point (output turns ON); B_{RPx} = release point (output turns OFF). 3. Typical Data is at T_A = +25°C and V_{DD} = 2.75 V and is for design information only.

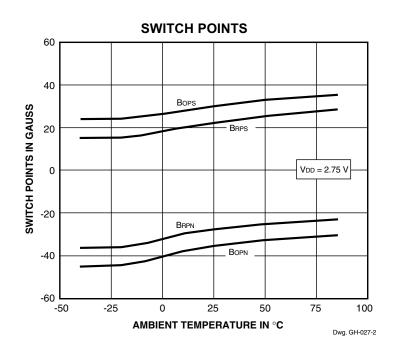
MAGNETIC CHARACTERISTICS with $C_{BYPASS} = 0.1 \mu F$, over operating voltage and temperature range (unless otherwise specified).

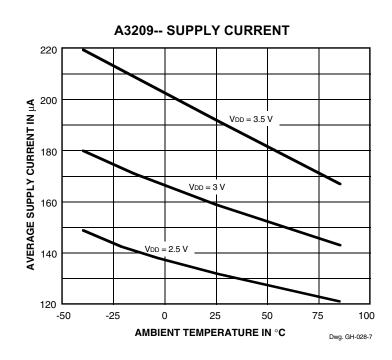
| | | | Limits | | | |
|----------------|------------------|-------------------------------------|--------|------|------|-------|
| Characteristic | Symbol | Test Conditions | Min. | Тур. | Max. | Units |
| Operate Points | B _{OPS} | South pole to branded side | _ | 30 | 60 | G |
| | B _{OPN} | North pole to branded side | -60 | -35 | _ | G |
| Release Points | B _{RPS} | South pole to branded side | 5.0 | 22 | _ | G |
| | B _{RPN} | North pole to branded side | _ | -27 | -5.0 | G |
| Hysteresis | B _{hys} | B _{OPx} - B _{RPx} | _ | 7.7 | =. | G |

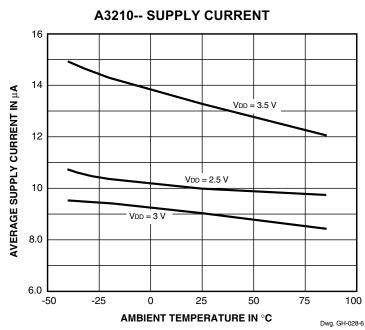
NOTES: 1. As used here, negative flux densities are defined as less than zero (algebraic convention) and -50 G is less than +10 G.

^{2.} Typical Data is at $T_A = +25$ °C and $V_{DD} = 2.75$ V and is for design information only.

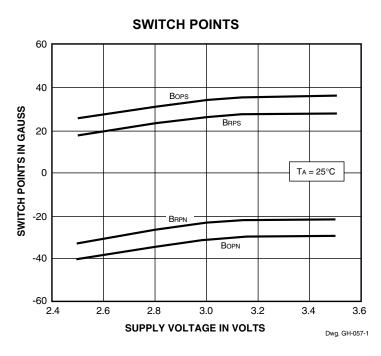
TYPICAL OPERATING CHARACTERISTICS as a function of temperature

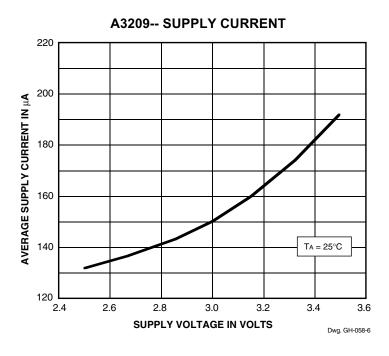


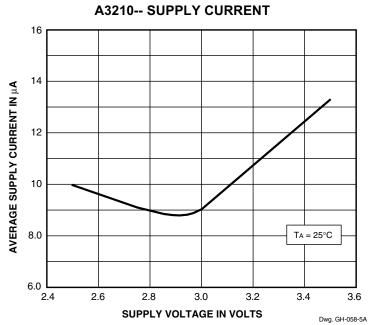




TYPICAL OPERATING CHARACTERISTICS as a function of supply voltage







3209 AND 3210 MICROPOWER, ULTRA-SENSITIVE HALL-EFFECT SWITCHES

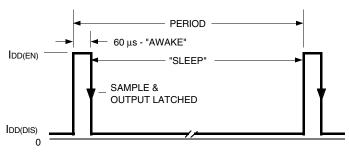
CRITERIA FOR DEVICE QUALIFICATION

All Allegro sensors are subjected to stringent qualification requirements prior to being released to production. To become qualified, except for the destructive ESD tests, no failures are permitted.

| Qualification Test | Test Method and Test Conditions | Test Length | Samples | Comments |
|---|--|---------------------|---------------|---------------------------------------|
| Biased Humidity (HAST) | T _A = 130°C, RH = 85% | 50 hrs | 77 | $V_{DD} = V_{OUT} = 3 V$ |
| High-Temperature Operating Life (HTOL) | JESD22-A108, T _A = 150°C, T _J ≤ 165°C | 408 hrs | 77 | $V_{DD} = V_{OUT} = 3 V$ |
| Accelerated HTOL | $T_A = 175^{\circ}C, T_J \le 190^{\circ}C$ | 504 hrs | 77 | $V_{DD} = V_{OUT} = 3 V$ |
| Autoclave, Unbiased | JESD22-A102, Condition C, $T_A = 121^{\circ}C$, 15 psig | 96 hrs | 77 | |
| High-Temperature (Bake) Storage Life | MIL-STD-883, Method 1008, T _A = 170°C | 1000 hrs | 77 | |
| Temperature Cycle | MIL-STD-883, Method 1010, -65°C to +150°C | 500 cycles | 77 | |
| Latch-Up | _ | Pre/Post Reading | 6 | |
| Electro-Thermally Induced Gate Leakage | _ | Pre/Post Reading | 6 | |
| ESD, Human Body Model | CDF-AEC-Q100-002 | Pre/Post Reading | 3 per test | Test to failure, All leads > 5 kV |
| ESD, Machine Model | JESD22-A115 | Pre/Post Reading | 3 per test | Test to failure, All leads > 350 V |
| Electrical Distributions | Per Specification | _ | 30 | |

FUNCTIONAL DESCRIPTION

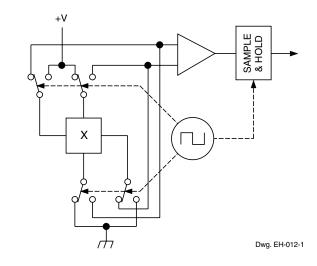
Low Average Power. Internal timing circuitry activates the sensor for $60~\mu s$ and deactivates it for the remainder of the period ($480~\mu s$ for the A3209Ex and 60~ms for the A3210Ex). A short "awake" time allows for stabilization prior to the sensor sampling and data latching on the falling edge of the timing pulse. The output during the "sleep" time is latched in the last sampled state. The supply current is not affected by the output state.

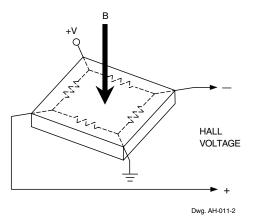


Dwa. WH-017-1

Chopper-Stabilized Technique. The Hall element can be considered as a resistor array similar to a Wheatstone bridge. A large portion of the offset is a result of the mismatching of these resistors. These devices use a proprietary dynamic offset cancellation technique, with an internal high-frequency clock to reduce the residual offset voltage of the Hall element that is normally caused by device overmolding, temperature dependencies, and thermal stress. The chopper-stabilizing technique cancels the mismatching of the resistor circuit by changing the direction of the current flowing through the Hall plate using CMOS switches and Hall voltage measurement taps, while maintaing the Hall-voltage signal that is induced by the external magnetic flux. The signal is then captured by a sample-andhold circuit and further processed using low-offset bipolar circuitry. This technique produces devices that have an extremely stable quiescent Hall output voltage, are immune to thermal stress, and have precise recoverability after temperature cycling. This technique will also slightly degrade the device output repeatability. A relatively high sampling frequency is used in order that faster signals can be processed.

More detailed descriptions of the circuit operation can be found in: Technical Paper STP 97-10, Monolithic Magnetic Hall Sensor Using Dynamic Quadrature Offset Cancellation and Technical Paper STP 99-1, Chopper-Stabilized Amplifiers With A Track-and-Hold Signal Demodulator.

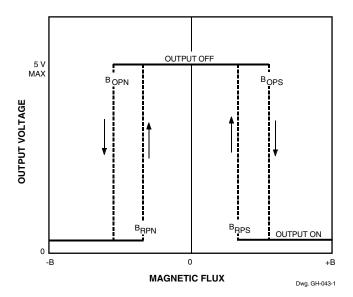




Operation. The output of this device switches low (turns on) when a magnetic field perpendicular to the Hall sensor exceeds the operate point B_{OPS} (or is less than B_{OPN}). After turn-on, the output is capable of sinking up to 1 mA and the output voltage is $V_{OUT(ON)}$. When the magnetic field is reduced below the release point B_{RPS} (or increased above B_{RPN}), the device output switches high (turns off). The difference in the magnetic operate and release points is the hysteresis (B_{hys}) of the device. This built-in hysteresis allows clean switching of the output even in the presence of external mechanical vibration and electrical noise.

As used here, negative flux densities are defined as less than zero (algebraic convention) and -50 G is less than +10 G.

3209 AND 3210 MICROPOWER, ULTRA-SENSITIVE HALL-EFFECT SWITCHES

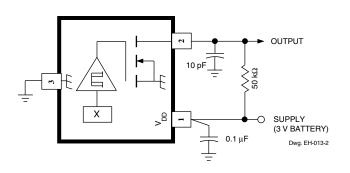


Applications. Allegro's pole-independent sensing technique allows for operation with either a north pole or south pole magnet orientation, enhancing the manufacturability of the device. The state-of-the-art technology provides the same output polarity for either pole face.

It is strongly recommended that an external bypass capacitor be connected (in close proximity to the Hall sensor) between the supply and ground of the device to reduce both external noise and noise generated by the chopper-stabilization technique. This is especially true due to the relatively high impedance of battery supplies.

The simplest form of magnet that will operate these devices is a bar magnet with either pole near the branded surface of the device. Many other methods of operation are possible. Extensive applications information on magnets and Hall-effect sensors is also available in the *Allegro Electronic Data Book* AMS-702 or *Application Note* 27701, or at

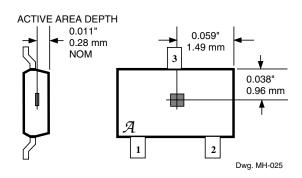
www.allegromicro.com



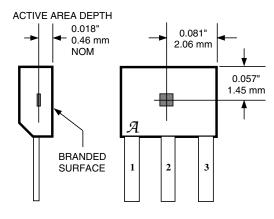
SENSOR LOCATIONS

(±0.005" [0.13 mm] die placement)

Package Designator 'LH'



Package Designators 'UA', UA-LC', and 'UA-TL'



Dwg. MH-011-11

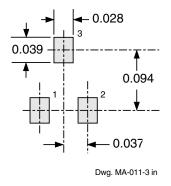
Although sensor location is accurate to three sigma for a particular design, product improvements may result in small changes to sensor location.

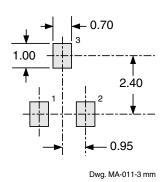


PACKAGE DESIGNATOR 'LH'

(fits SC-74A solder-pad layout)

Dimensions in Inches Dimensions in Millimeters (controlling dimensions) (for reference only) 3.10 2.90 0.122 0.114 0.50 0.0079 0.20 0.020 0.30 0.0050 0.127 0.0122.10 0.083 3.00 0.118 0.020 MIN 0.25 MIN 1.85 0.073 2.70 0.106 0.022 0.55 0° to 8° 0° TO 8° REF **REF** 0.037 0.95 BSC 0.043 1.10 0.035 0.90 0.006 0.15 0.049 0.000 0.00 0.035 Dwg. MA-010-3B in Dwg. MA-010-3B mm





NOTES: 1. Tolerances on package height and width represent allowable mold offsets. Dimensions given are measured at the widest point (parting line).

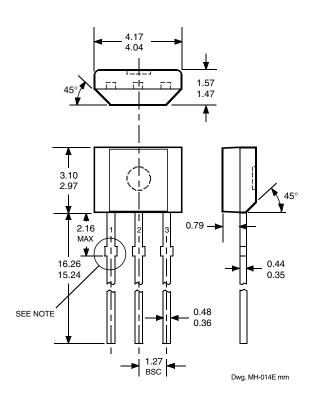
- 2. Exact body and lead configuration at vendor's option within limits shown.
- 3. Height does not include mold gate flash.
- 4. Where no tolerance is specified, dimension is nominal.

PACKAGE DESIGNATOR 'UA'

Dimensions in Inches (controlling dimensions)

0.159 0.062 0.058 0.122 0.031 0.085 MAX 0.640 0.0173 0.0138 SEE NOTE 0.0189 0.0142 0.050 BSC Dwg. MH-014E in

Dimensions in Millimeters (for reference only)



NOTES: 1. Tolerances on package height and width represent allowable mold offsets. Dimensions given are measured at the widest point (parting line).

- 2. Exact body and lead configuration at vendor's option within limits shown.
- 3. Height does not include mold gate flash.
- 4. Recommended minimum PWB hole diameter to clear transition area is 0.035" (0.89 mm).
- 5. Where no tolerance is specified, dimension is nominal.

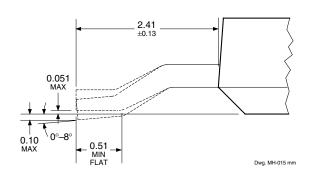


Surface-Mount Lead Form (order A32xxEUA-TL)

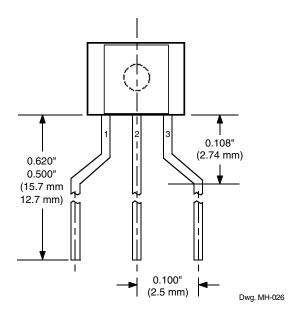
Dimensions in Inches (controlling dimensions)

0.002 MAX 0.004 0°-8° 0.020 MIN FLAT Dwg. MH-015 in

Dimensions in Millimeters (for reference only)



Radial Lead Form (order A32xxEUA-LC)



NOTE: Lead-form dimensions are the nominals produced on the forming equipment. No dimensional tolerance is implied or guaranteed for bulk packaging (500 pieces per bag).

The products described herein are manufactured under one or more of the following U.S. patents: 5,045,920; 5,264,783; 5,442,283; 5,389,889; 5,581,179; 5,517,112; 5,619,137; 5,621,319; 5,650,719; 5,686,894; 5,694,038; 5,729,130; 5,917,320; and other patents pending.

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The information included herein is believed to be accurate and reliable. However, Allegro MicroSystems, Inc. assumes no responsibility for its use; nor for any infringements of patents or other rights of third parties that may result from its use.

HALL-EFFECT SENSORS

| Partial Part | Avail. Oper | . Charac | cteristics at | Т _Д = +25°С | | | |
|--|-------------|----------|---------------|------------------------|---|----------|--|
| Number | Temp. | BOP max | BRP min | B _{hys} typ | Features | Notes | |
| HALL-EFFECT UNIPOLAR & OMNIPOLAR SWITCHES in order of B _{OP} and B _{hys} | | | | | | | |
| 3240 | E/L | +50 | +5.0 | 10 | chopper stabilized | 1 | |
| 3209 | E | ±60 | ±5.0 | 7.7 | 400 μW, chopper stabilized | | |
| 3210 | E | ±60 | ±5.0 | 7.7 | 25 μW, chopper stabilized | | |
| 3361 | E | +125 | +40 | 5.0* | 2-wire, chopper stabilized, inverte | d output | |
| 3362 | E E | +125 | +40 | 5.0* | 2-wire, chopper stabilized | • | |
| 3161 | E | +160 | +30 | 20 | 2-wire | | |
| 3141 | E/L | +160 | +10 | 55 | | | |
| 3235 | S | +175 | +25 | 15* | output 1 | 2 | |
| | | -25 | -175 | 15* | output 2 | 2 2 | |
| 5140 | E | +200 | +50 | 55 | 300 mA power driver output | 1 | |
| 3142 | E/L | +230 | +75 | 55 | F | | |
| 3143 | E/L | +340 | +165 | 55 | | | |
| 3144 | E/L | +350 | +50 | 55 | | | |
| 3122 | E/L | +400 | +140 | 105 | | | |
| 3123 | E/L | +440 | +180 | 105 | | | |
| 3121 | E/L | +450 | +125 | 105 | | | |
| | | | | | + | | |
| | | | | | [†] in order of BOP and B _{hys} | | |
| 3260 | E/L | +30 | -30 | 20 | bipolar switch, chopper stabilized | | |
| 3280 | E/L | +40 | -40 | 45 | chopper stabilized | | |
| 3134 | E/L | +50 | -50 | 27 | bipolar switch | | |
| 3133 | K/L/S | +75 | -75 | 52 | bipolar switch | | |
| 3281 | E/L | +90 | -90 | 100 | chopper stabilized | | |
| 3132 | K/L/S | +95 | -95 | 52 | bipolar switch | | |
| 3187 | E/L | +150 | -150 | 100* | | | |
| 3177 | S | +150 | -150 | 200 | | | |
| 3625 | S | +150 | -150 | 200 | 900 mA power driver output | 1, 3 | |
| 3626 | S | +150 | -150 | 200 | 400 mA power driver output | 1, 3 | |
| 3195 | E/L | +160 | -160 | 220 | active pulldown | 1 | |
| 3197 | L | +160 | -160 | 230 | • | 1 | |
| 3175 | S | +170 | -170 | 200 | | | |
| 3188 | E/L | +180 | -180 | 200* | | | |
| 3283 | E/L | +180 | -180 | 300 | chopper stabilized | | |
| 3189 | E/L | +230 | -230 | 100* | • • | | |
| 3275 | S | +250 | -250 | 100* | | 3 | |
| 3185 | E/L | +270 | -270 | 340* | | • | |
| 3100 | -/ L | . 210 | 210 | 0-10 | | | |

Operating Temperature Ranges:

 $S = -20^{\circ}C$ to $+85^{\circ}C$, $E = -40^{\circ}C$ to $+85^{\circ}C$, $J = -40^{\circ}C$ to $+115^{\circ}C$, $K = -40^{\circ}C$ to $+125^{\circ}C$, $L = -40^{\circ}C$ to $+150^{\circ}C$

Notes 1. Protected.



^{2.} Output 1 switches on south pole, output 2 switches on north pole for 2-phase, bifilar-wound, unipolar-driven brushless dc motor control. Outputs may be tied together for omnipolar operation.

^{3.} Complementary outputs for 2-phase bifilar-wound, unipolar-driven brushless dc motor control.

^{*} Minimum. ‡ Maximum

[†] Latches will <u>not</u> switch on removal of magnetic field; bipolar switches <u>may</u> switch on removal of field but require field reversal for reliable operation over operating temperature range.